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REVISION HISTORY

Version	Date	Page	Description
1.0	2025.6	All	Approval Specification was first issued.
1.1	2025.8.4	P6&P28	Update Drawing pin1
2.0	2025.9.4	P7/9~12	Update EE
		P18	Update OPT Luminance
		P27	Update Drawing
3.0	20251015	P5	刪除 262K 字眼
4.0	2026/1/6	P7	Update Converter Voltage 26V=>24V
		P18	Update RGB
5.0	2026/3/10	P18	Update RGB

1. GENERAL DESCRIPTION

1.1 OVERVIEW

G238HCB-LA1 is a 23.8" TFT Liquid Crystal Display IAV module with mini LED Backlight unit and LVDS interface. This module supports 1920 x 1080 Full HD mode and can display up to 16.7M colors.

1.2 FEATURE

- FHD (1920 x 1080 pixels) resolution
- Wide operating temperature.
- RoHS compliance

1.3 APPLICATION

- TFT LCD Monitor
- Factory Application

1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	527.04 (H) x 296.46 (V)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	1920 x R.G.B x 1080	pixel	-
Pixel Pitch	0.2745 (H) x 0.2745 (V)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	16.7M	color	-
Display Mode	Normally Black	-	-
Surface Treatment	AG type, 3H hard coating	-	-
Module Power Consumption	Total (58.25) W (Max.) @ Cell 7.25W (Max.), BL (51)W (Max.)	W	Typ.

1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Typ.	Max.	Unit	Note
Module Size	Horizontal(H) (w/o screw)	(542.5)	(543)	(543.5)	mm	(1)
	Vertical(V) (w/o screw)	(316.9)	(317.4)	(317.9)	mm	
	Depth(D) (w/o standoff)	(11)	(11.5)	(12)	mm	(1)(2)
Bezel Area	Horizontal	(529.7)	(530.2)	(530.7)	mm	-
	Vertical	(299.1)	(299.6)	(300.1)	mm	
Active Area	Horizontal	--	527.04	--	mm	
	Vertical	--	296.46	--	mm	
Weight				(2300)	g	

Note (1)Please refer to the attached drawings for more information of front and back outline dimensions.

Note (2)Depth(D) without standoff and PCBa.

2. ABSOLUTE MAXIMUM RATINGS

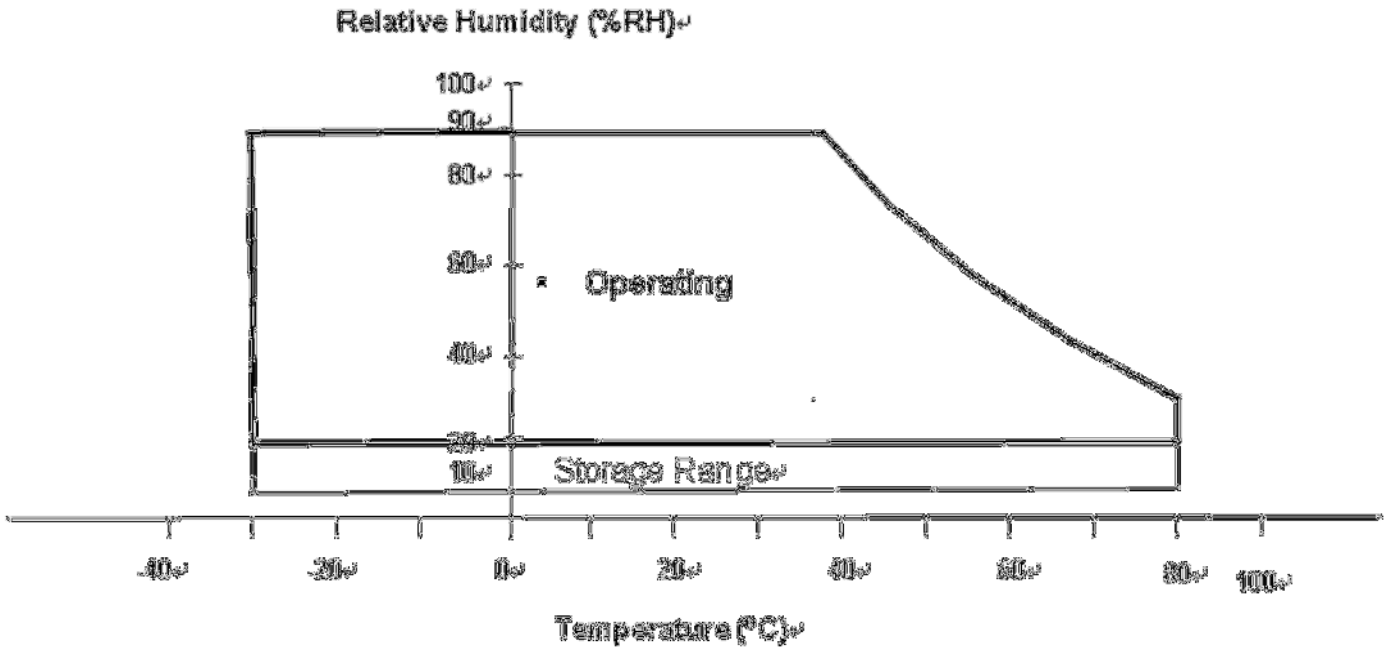
2.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Operating Ambient Temperature	T _{OP}	-30	+80	°C	(1)(2)
Storage Temperature	T _{ST}	-30	+80	°C	

Note (1)

- (a) 90 %RH Max.
- (b) Wet-bulb temperature should be 39 °C Max.
- (c) No condensation.

Note (2) Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than 80°C (Panel surface temperature) .



2.2 ELECTRICAL ABSOLUTE RATINGS

2.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Power Supply Voltage	VCC	-0.3V	6	V	(1)

2.2.2 BACKLIGHT UNIT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Converter Voltage	V_i	-0.3V	24	V	(1), (2)
Enable Voltage	EN	-0.3V	5	V	
Backlight Adjust	Dimming	-0.3V	5	V	

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for LED (Refer to 3.2 for further information).

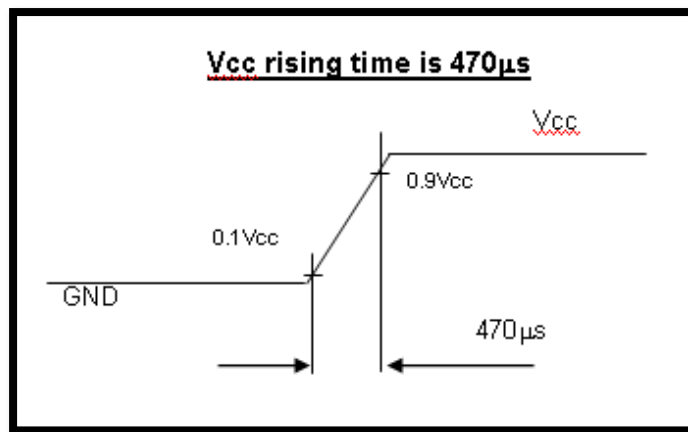
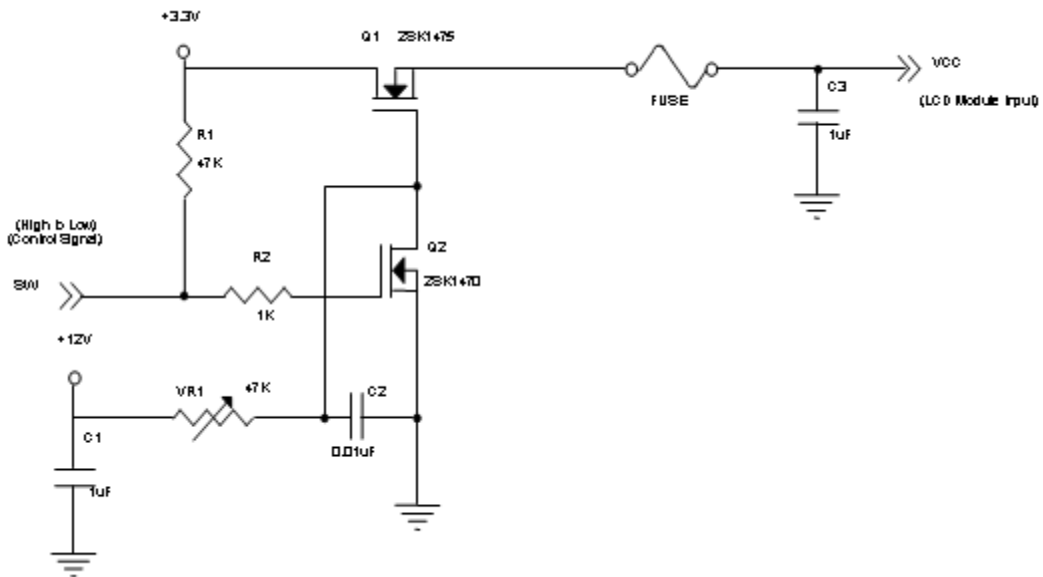
3. ELECTRICAL CHARACTERISTICS

3.1 TFT LCD MODULE

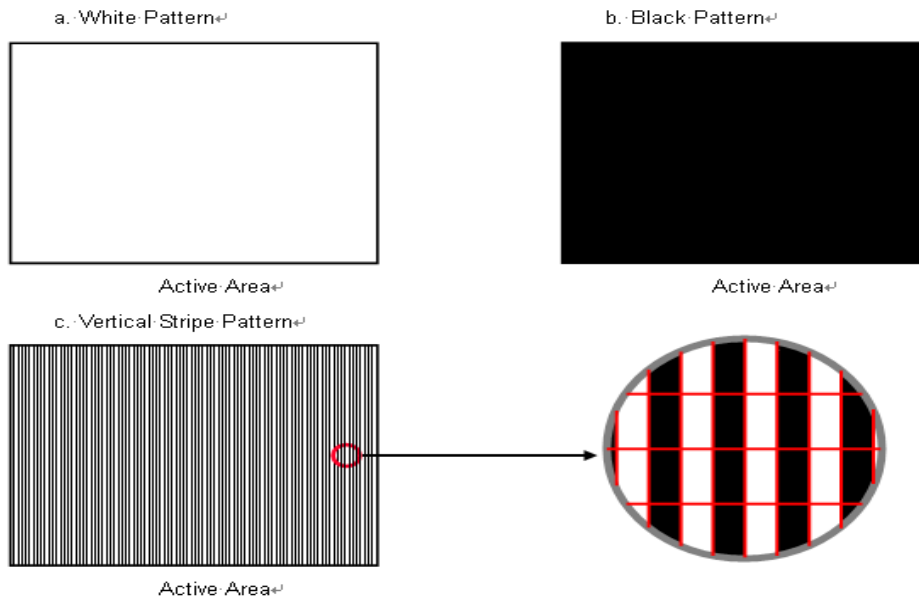
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
Power Supply Voltage	V _{CC}	(4.5)	(5.0)	(5.5)	V	-
Ripple Voltage	V _{RP}	-	-	(400)	mVp-p	
Inrush Current	I _{INRUSH}	-	-	(3.0)	A	(2)
Power Supply Current	White	-	(0.99)	(1.45)	A	(3)a
	Black	-	(0.45)	(0.5)	A	(3)b
	Vertical Stripe	-	(0.74)	(0.81)	A	(3)c
LVDS differential input voltage	V _{id}	(100)	-	(600)	mV	
LVDS common input voltage	V _{ic}	(1.0)	(1.2)	(1.4)	V	
Differential Input Voltage for LVDS Receiver Threshold	"H" Level	V _{IH}	-	(100)	mV	-
	"L" Level	V _{IL}	(-100)	-	mV	-
Terminating Resistor	R _T	-	(100)	-	Ohm	-

Note (1)The module should be always operated within above ranges.

Note (2)Measurement Conditions:



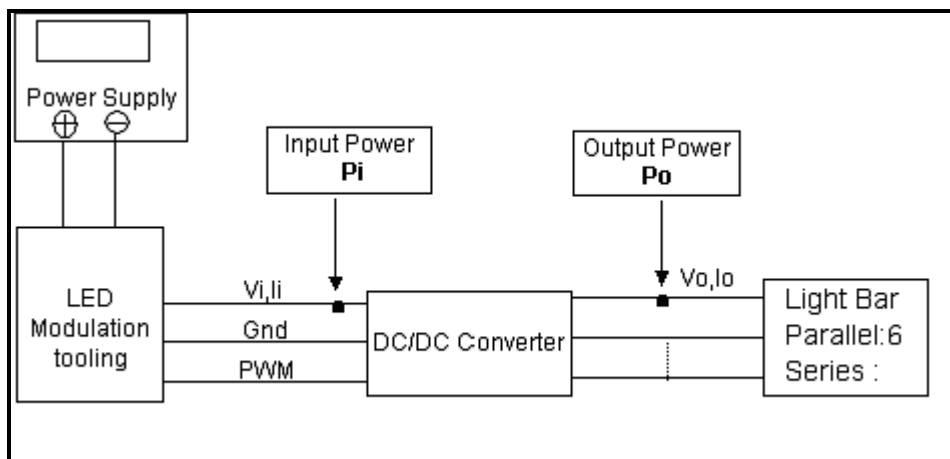
Note (3) The specified power supply current is under the conditions at $V_{CC} = 5V$, $T_a = 25 \pm 2 \text{ }^\circ\text{C}$, DC Current and $f_v = 60 \text{ Hz}$, whereas a power dissipation check pattern below is displayed.



3.2 BACKLIGHT UNIT

Parameter	Symbol	Value			Unit	Note	
		Min.	Typ.	Max.			
Converter Input Voltage	V_i	23	23.5	24	V_{DC}	(Duty 100%)	
Converter Input Ripple Voltage	V_{iRP}	-	-	(500)	mV		
Converter Input Current	I_i	-	(2)	(2.17)	A _{DC}	(Duty 100%)	
Converter Inrush Current	I_{iRUSH}	-	-	(3)	A	V_i rising time = 470us($V_i = 23.5V$)	
Input Power Consumption	P_i	-	(47)	(51)	W	(1), @ $V_i = 23.5V$ (Duty 100%)	
EN Control Level	Backlight on	ENLED (BLON)	3.3	-	5	V	
	Backlight off		0	-	0.6	V	
LED_EN Impedance		R_{LED_EN}	444k	-		ohm	
PWM Control Level	PWM High Level	Dimming (E_PWM)	3.3	-	5	V	
	PWM Low Level		0	-	0.6	V	
PWM Control Permissive Ripple Voltage		V_{PWMPP}	-	-	100	mV	
PWM Control Frequency		f_{PWM}	--		(20k)	Hz	
PWM Dimming Control Duty Ratio		Duty	10		100		
LED Life Time		L_{LED}	(50K)			Hrs	(2)

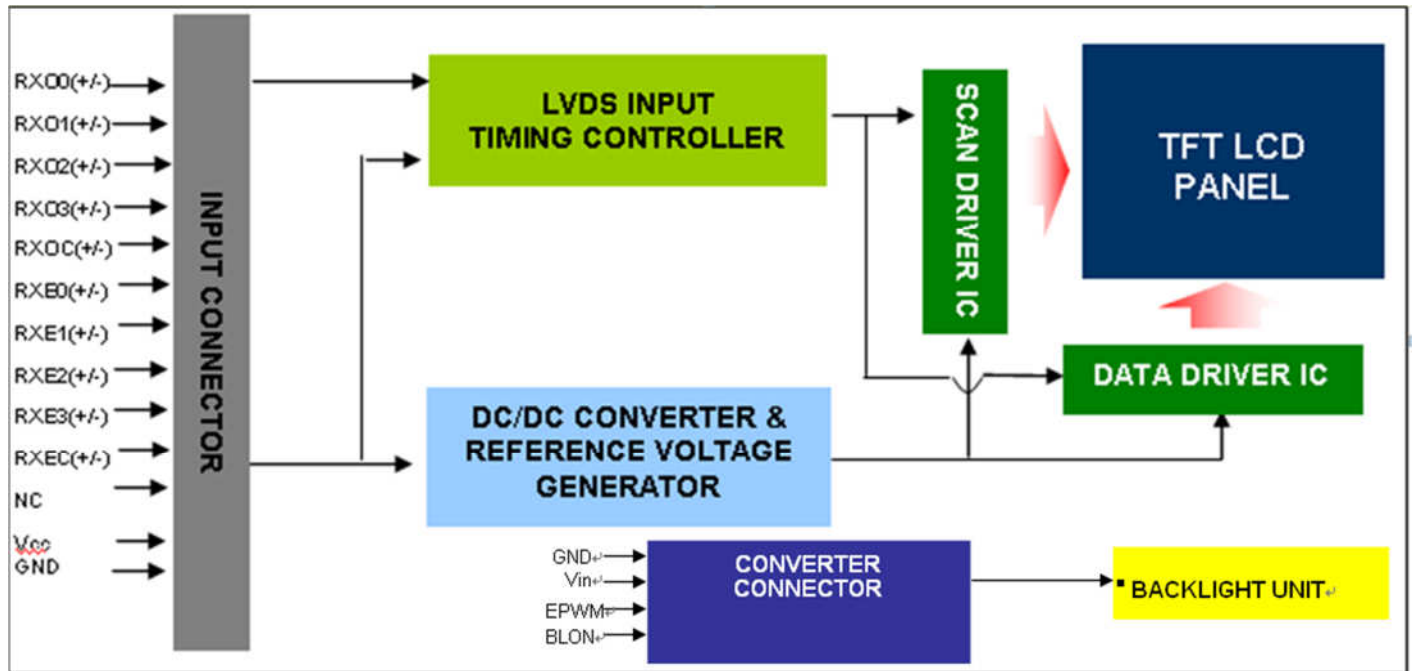
Note (1) LED current is measured by utilizing a high frequency current meter as shown below:



Note (2) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at $T_a = 25 \pm 2 \text{ }^\circ\text{C}$ and Duty 100% until the brightness becomes $\leq 50\%$ of its original value. Operating LED at high temperature condition will reduce life time and lead to color shift.

4. BLOCK DIAGRAM

4.1 TFT LCD MODULE



5. INPUT TERMINAL PIN ASSIGNMENT

5.1 TFT LCD MODULE (VESA ONLY)

Pin	Name	Description
1	RX00-	Negative LVDS differential data input. Channel O0 (odd)
2	RX00+	Positive LVDS differential data input. Channel O0 (odd)
3	RX01-	Negative LVDS differential data input. Channel O1 (odd)
4	RX01+	Positive LVDS differential data input. Channel O1 (odd)
5	RX02-	Negative LVDS differential data input. Channel O2 (odd)
6	RX02+	Positive LVDS differential data input. Channel O2 (odd)
7	GND	Ground
8	RXOC-	Negative LVDS differential clock input. (odd)
9	RXOC+	Positive LVDS differential clock input. (odd)
10	RX03-	Negative LVDS differential data input. Channel O3(odd)
11	RX03+	Positive LVDS differential data input. Channel O3 (odd)
12	RXE0-	Negative LVDS differential data input. Channel E0 (even)
13	RXE0+	Positive LVDS differential data input. Channel E0 (even)
14	GND	Ground
15	RXE1-	Negative LVDS differential data input. Channel E1 (even)
16	RXE1+	Positive LVDS differential data input. Channel E1 (even)
17	GND	Ground
18	RXE2-	Negative LVDS differential data input. Channel E2 (even)
19	RXE2+	Positive LVDS differential data input. Channel E2 (even)
20	RXEC-	Negative LVDS differential clock input. (even)
21	RXEC+	Positive LVDS differential clock input. (even)
22	RXE3-	Negative LVDS differential data input. Channel E3 (even)
23	RXE3+	Positive LVDS differential data input. Channel E3 (even)

24	GND	Ground
25	NC	For LCD internal use only, Do not connect
26	NC	For LCD internal use only, Do not connect
27	NC	For LCD internal use only, Do not connect
28	Vcc	V _i power supply
29	Vcc	V _i power supply
30	Vcc	V _i power supply

Note (1) Tcon PCBa Connector Part No.:

FCN: WF13-422-3033

P-TWO: 187098-30091 or equivalent.

Note (2) User's Plug Part No:

Mating Wire Cable's Connector Part No.: FI-30H(JAE) or FI-30HL(JAE) or equivalent.

Note (3) The first pixel is odd.

Note (4) Input signal of even and odd clock should be the same timing.

Please refer to Appendix Outline Drawing for detail design.

5.2 BACKLIGHT UNIT

Pin	Name	Description
1	V _{BL}	DC power supply
2		
3		
4		
5	GND	Ground
6		
7		
8		
9	NC	For BL internal use only, Do not connect
10	NC	For BL internal use only, Do not connect
11	NC	For BL internal use only, Do not connect
12	ENA	BL ON/OFF
13	NC	For BL internal use only, Do not connect
14	E_PWM	External PWM Control

Note (1) LED PCBa Connector Part No.: CviLux :CI0114M1HR0-LA-NH or FCN: JH2-D4-143N or equivalent.

Note (2) User's Plug Part No.: CviLux CI0114S0000 or equivalent.

5.3 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

Color		Data Signal																							
		Red								Green								Blue							
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
Basic Colors	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	
	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	
Gray Scale Of Red	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Red(1)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Red(2)	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮		
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮		
	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
Gray Scale Of Green	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0		
	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0		
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮			
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮			
	Green(253)	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0		
	Green(254)	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0		
	Green(255)	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0		
Gray Scale Of Blue	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1		
	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0		
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮			
	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮			
	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0		
	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0		
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1		

Note (1)0: Low Level Voltage, 1: High Level Voltage

6. INTERFACE TIMING

6.1 INPUT SIGNAL TIMING SPECIFICATIONS

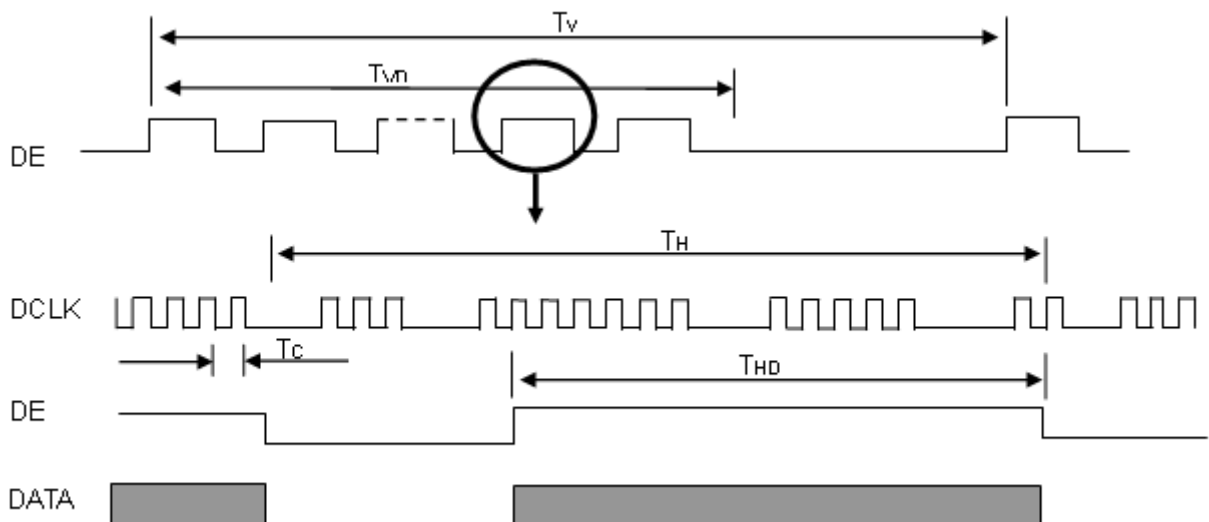
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
LVDS Clock	Frequency	Fc	58.54	74.25	97.98	MHz	-
	Period	Tc	-	13.47	-	ns	
	Input cycle to cycle jitter	T _{rcj}	-0.02*Tc	-	0.02*Tc	ns	(a)
	Input Clock to data skew	TLVCCS	-0.02*Tc	-	0.02*Tc	ps	(b)
	Spread spectrum modulation range	F _{clk_{in}_mod}	0.97*Fc	---	1.03*Fc	MHz	(c)
	Spread spectrum modulation frequency	F _{SSM}	---	---	100	KHz	
Vertical Display Term	Frame Rate	Fr	50	60	75	Hz	Tv=Tvd+Tvb
	Total	Tv	1110	1125	1220	Th	-
	Active Display	Tvd	1080	1080	1080	Th	-
	Blank	Tvb	Tv-Tvd	45	Tv-Tvd	Th	-
Horizontal Display Term	Total	Th	1050	1100	1150	Tc	Th=Thd+Thb
	Active Display	Thd	960	960	960	Tc	-
	Blank	Thb	Th-Thd	140	Th-Thd	Tc	-

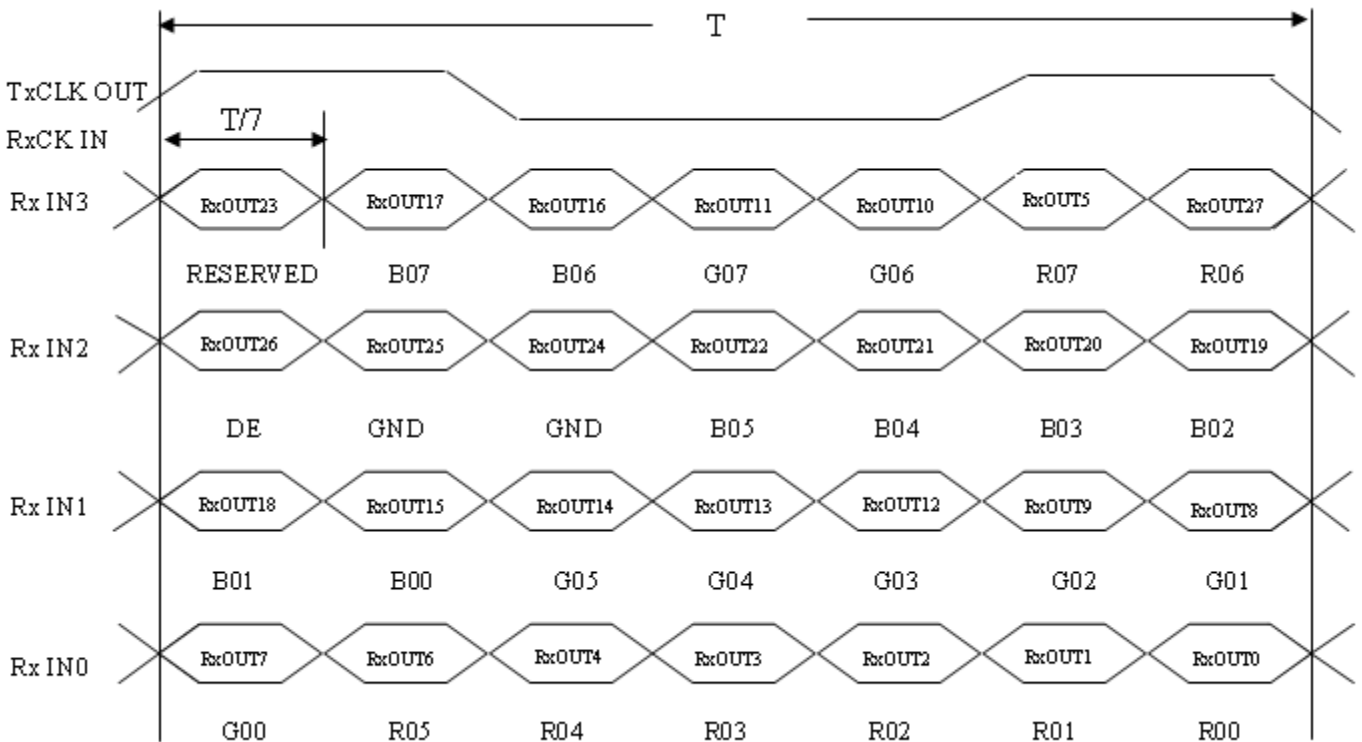
Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

Note (2) The Tv(Tvd+Tvb) must be integer, otherwise, the module would operate abnormally.

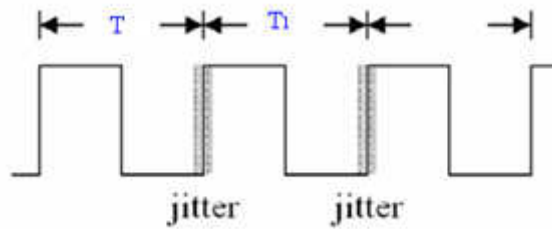
INPUT SIGNAL TIMING DIAGRAM



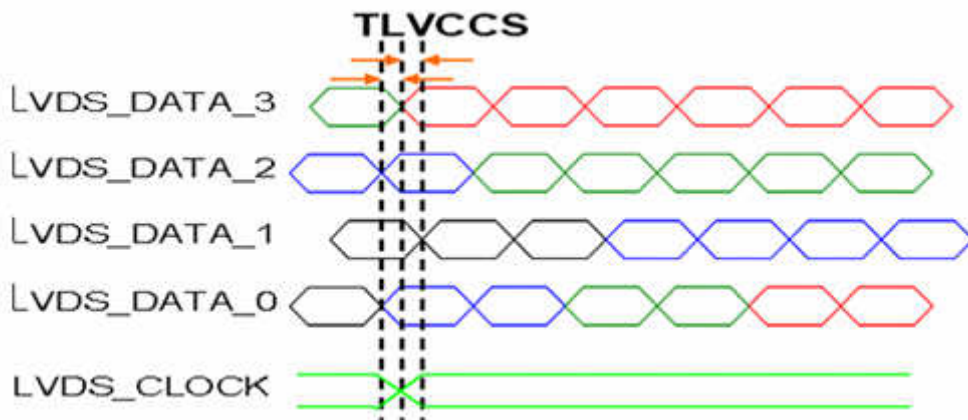
TIMING DIAGRAM of LVDS



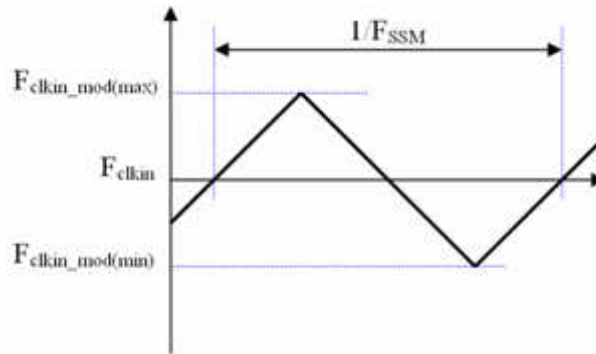
Note (a) The input clock cycle-to-cycle jitter is defined as below figures. $T_{rd} = |T1 - T1|$



Note (b) Input Clock to data skew is defined as below figures.

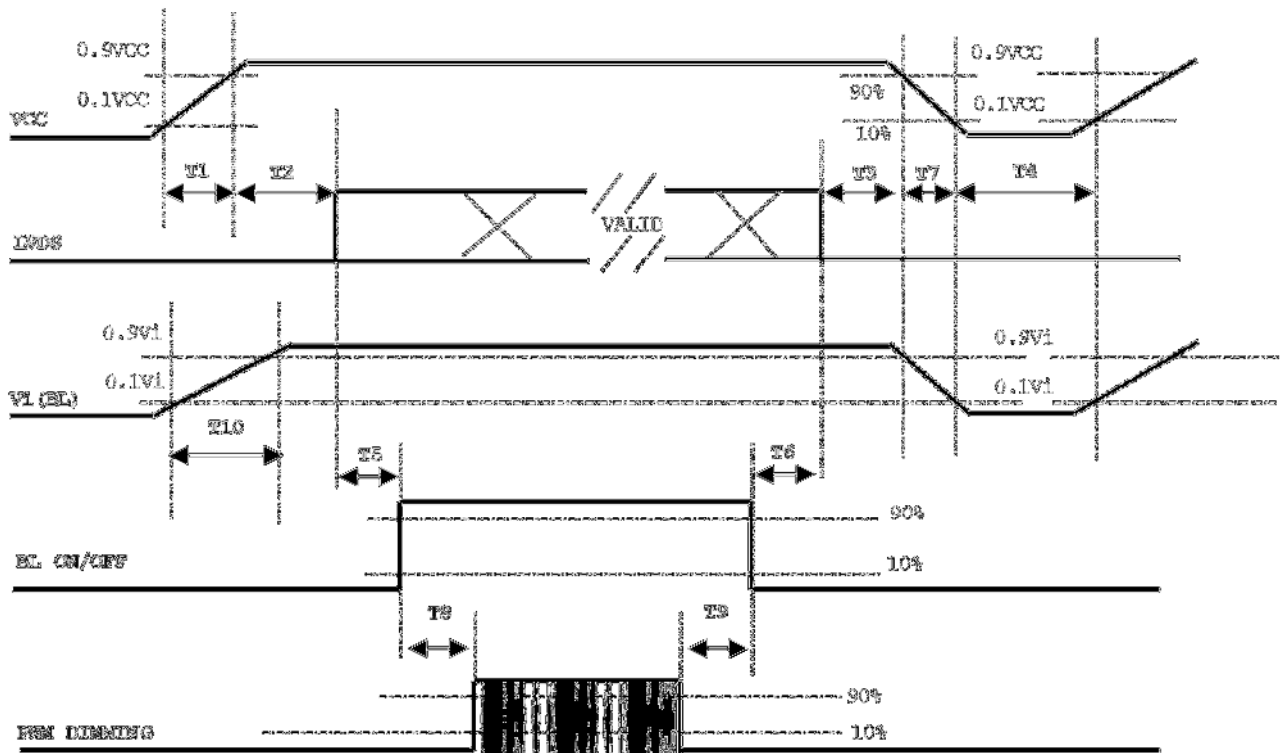


Note (c) The SSCG (Spread spectrum clock generator) is defined as below figures.



6.2 POWER ON/OFF SEQUENCE

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



Parameter	Value			Units Min
	Min	Typ	Max	
T1	0.5	-	10	ms
T2	0	-	50	ms
T3	0	-	50	ms
T4	500	-	-	ms
T5	450	-	-	ms
T6	200	-	-	ms
T7	10	-	100	ms
T8	10	-	-	ms
T9	10	-	-	ms
T10	20	-	50	ms

Note:

- (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.
- (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.
- (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.
- (4) T4 should be measured after the module has been fully discharged between power off and on period.
- (5) Interface signal shall not be kept at high impedance when the power is on.
- (6) INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.
- (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "T7 spec".

7. OPTICAL CHARACTERISTICS

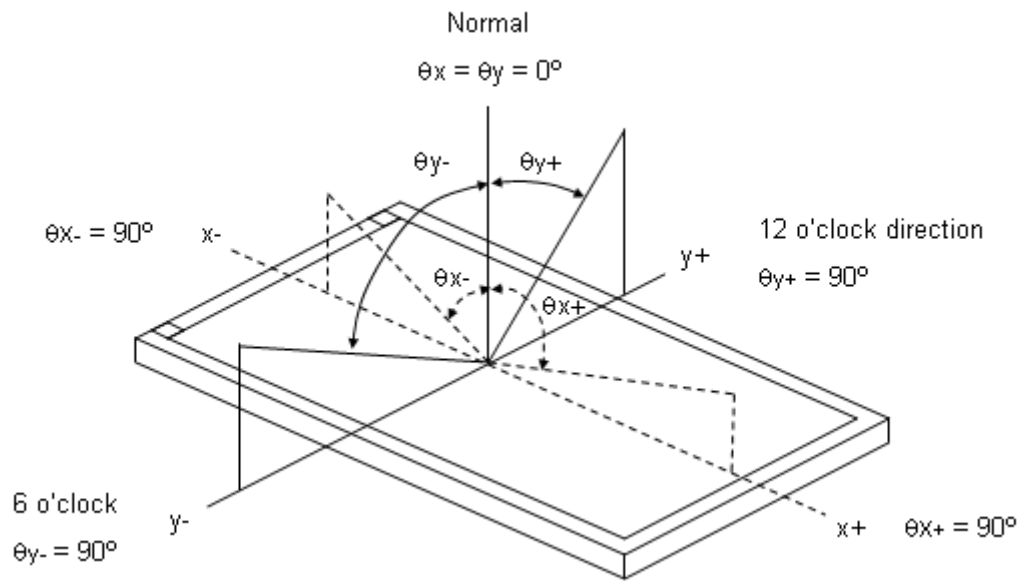
7.1 TEST CONDITIONS

LCD is driving at frame rate 60Hz in room temperature 25°C.

7.2 OPTICAL SPECIFICATIONS

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Color Chromaticity	Red	Rx	$\theta X=0^\circ, \theta Y=0^\circ$	0.641	0.691	0.741	-	(4)
		Ry		0.253	0.303	0.353		
	Green	Gx		0.162	0.212	0.262		
		Gy		0.674	0.724	0.774		
	Blue	Bx		0.103	0.153	0.203		
		By		0.009	0.059	0.109		
	White	Wx		0.263	0.313	0.363		
		Wy		0.279	0.329	0.379		
Luminance		L		1600	2000	-		(4)
Contrast Ratio		CR		700	1000	-	-	(2), (4)
Response Time		Ton+Toff	$\theta X=0^\circ, \theta Y=0^\circ$			35		(3)
Luminance Uniformity		U%	$\theta X=0^\circ, \theta Y=0^\circ$	80	85	-	%	(5)
Viewing Angle	Horizontal	$\theta X+$	$CR \geq 10$	80	-	-	Deg.	(1), (4)
		$\theta X-$		80	-	-		
	Vertical	$\theta Y+$		80	-	-		
		$\theta Y-$		80	-	-		

Note (1) Definition of Viewing Angle (θ_x, θ_y):

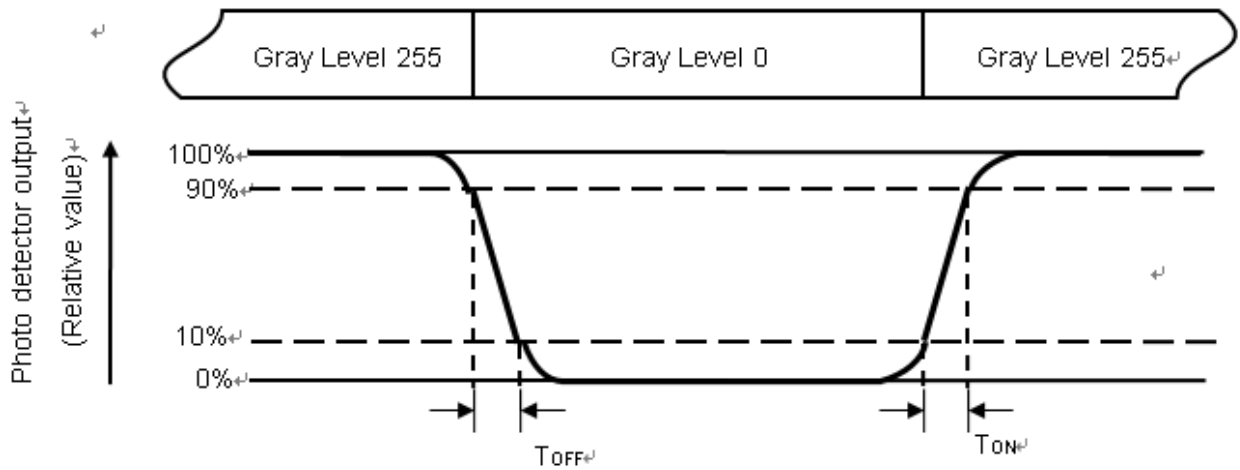


Note (2) Definition of Contrast Ratio (CR):

$$\text{Contrast Ratio (CR)} = \text{luminance of L255} / \text{luminance of L0}$$

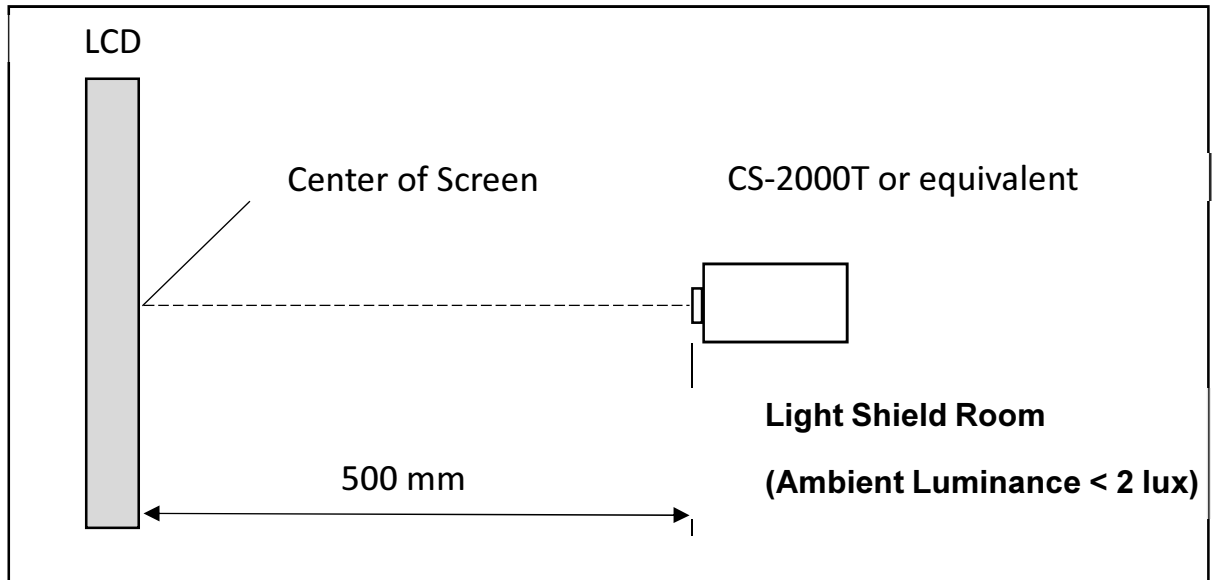
Note (3) Definition of Response Time :

The response time is defined as the time interval between the 10% and 90% of amplitudes which measured by DMS-900 & oscilloscope 5034B



Note (4) Measurement Setup:

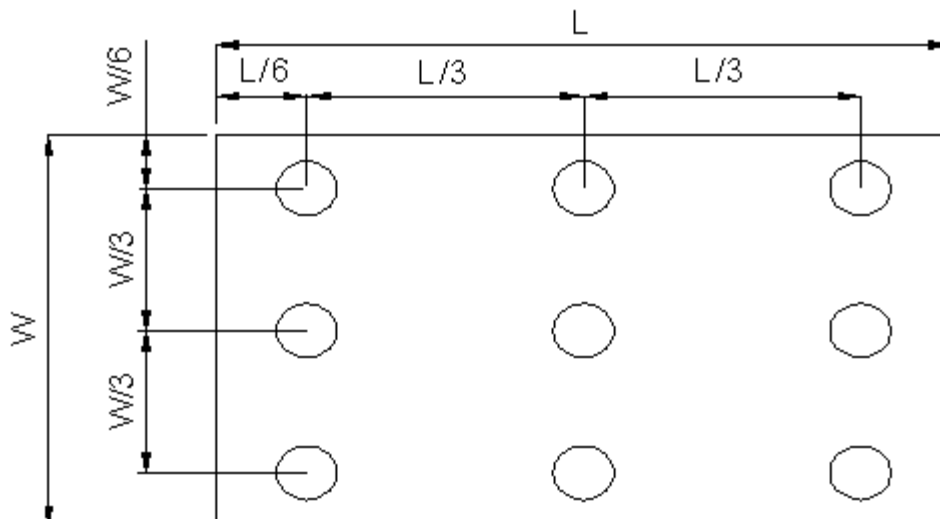
The LCD module should be stabilized at given temperature for 10 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 10 minutes in a windless room.



Note (5): Definition of luminance uniformity:

Measure the luminance of gray level 255 at 9 points

$$\text{Luminance Uniformity} = \frac{L_{\min}}{L_{\max}}$$



L_{\max} : The measured maximum luminance of all measurement position.

L_{\min} : The measured minimum luminance of all measurement position

8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note
High Temperature Storage Test	80°C, 240 hours	(1),(2) (4),(5)
Low Temperature Storage Test	-30°C, 240 hours	
Thermal Shock Storage Test	-20°C, 0.5 hour ↔ 60°C, 0.5 hour; 100cycles, 1 hour/cycle)	
High Temperature Operation Test	80°C, 240 hours	
Low Temperature Operation Test	-30°C, 240 hours	
High Temperature & High Humidity Operation Test	60°C, RH 90%, 240 hours	
ESD Test (Operation)	150pF, 330Ω, 1 sec/cycle Condition 1 : panel contact, ±8 KV Condition 2 : panel non-contact ±15 KV	(1), (4)
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for ± X, ± Y, ± Z direction	(2), (3)
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz sine wave, 10 min/cycle, 3 cycles each X, Y, Z direction	

Note (1) There should be no condensation on the surface of panel during test ,

Note (2) Temperature of panel display surface area should be 80°C Max. And it also should be followed by the de-rating condition as 3.2 Backlight Unit note (4).

Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.

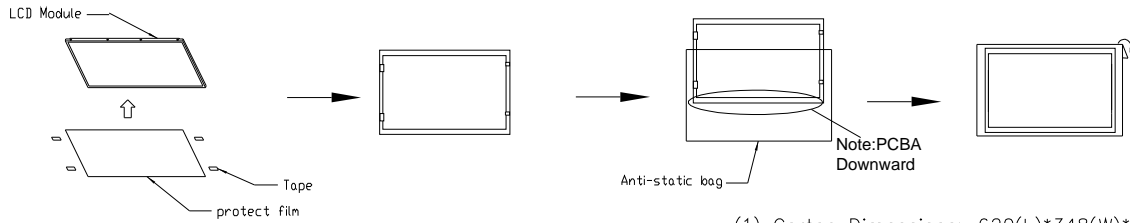
Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.

9. PACKAGING

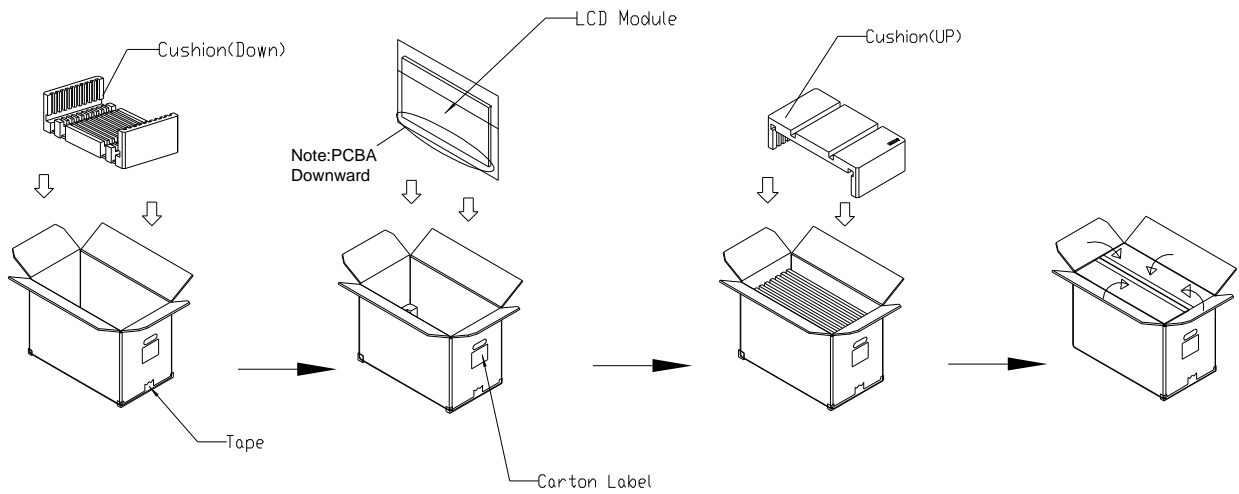
9.1 PACKING SPECIFICATIONS

- (1) 10 LCD modules / 1 Box
- (2) Box dimensions: 620(L) X 348(W) X 430(H) mm
- (3) Weight: approximately: 30.4kg (10 modules per box)

9.2 PACKING METHOD



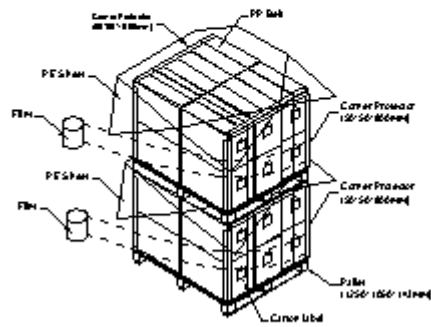
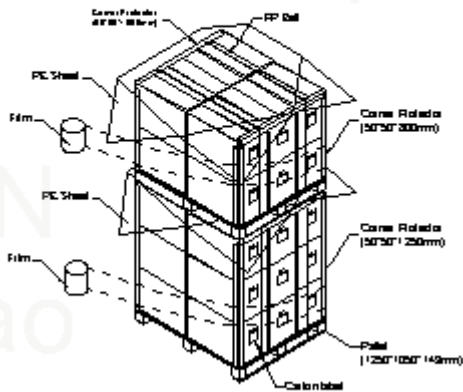
- (1) Carton Dimensions: 620(L)*348(W)*430(H)mm
- (2) 10 Modules/Carton



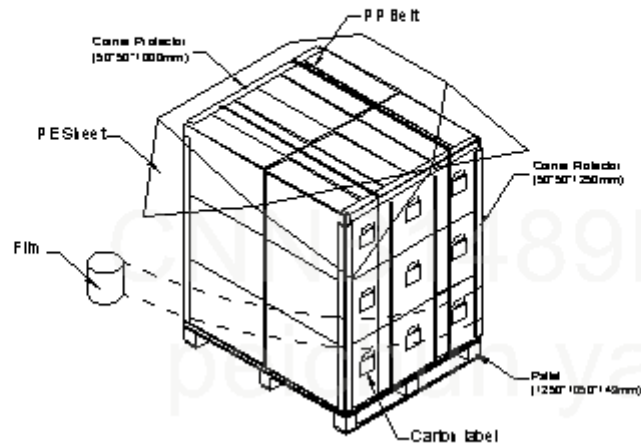
For ocean

Sea / Land Transportation (40ft HQ Container)

Sea / Land Transportation (40ft/20ft Container)



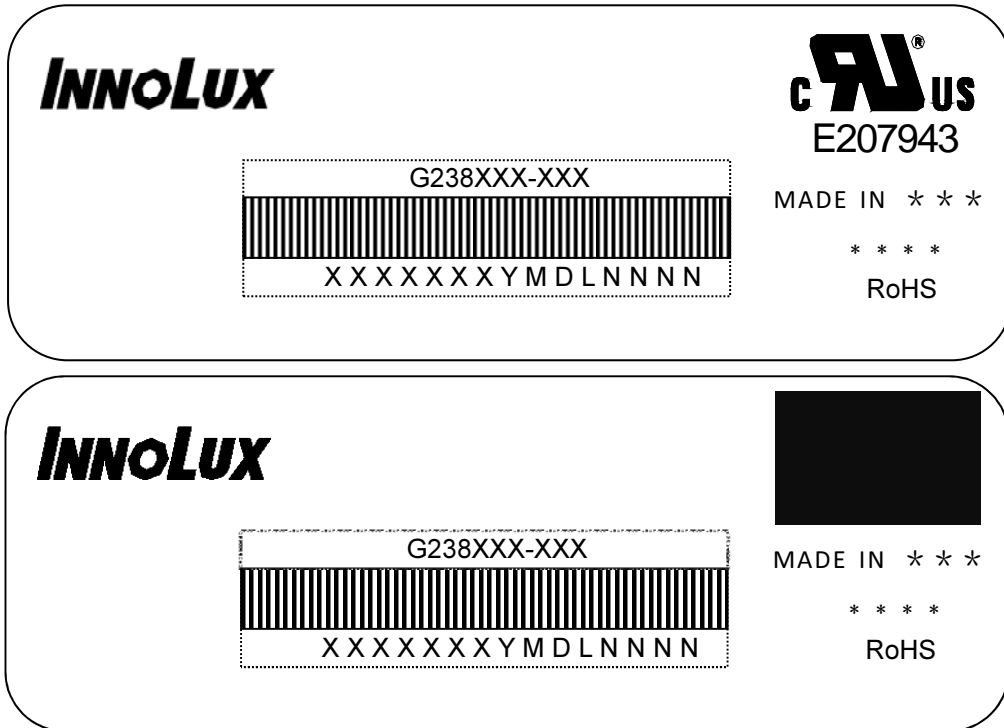
For air



10. DEFINITION OF LABELS

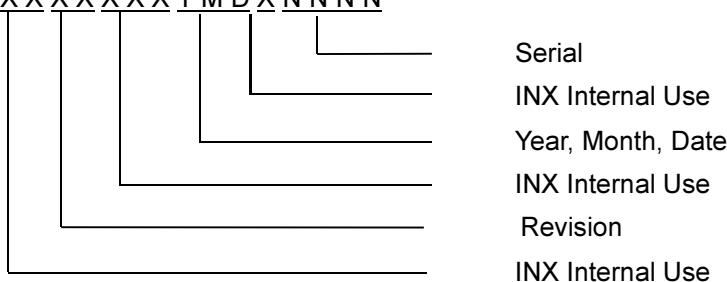
10.1 INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.



Note (1) Safety Compliance(UL logo) will open after C1 version.

- (a) Model Name: G238HCB-LA1
- (b) * * * * : Factory ID
- (c) Serial ID: X X X X X X Y M D X N N N N



Serial ID includes the information as below:

- (a) Manufactured Date: Year: 1~9, for 2021~2029
 Month: 1~9, A~C, for Jan. ~ Dec.
 Day: 1~9, A~Y, for 1st to 31st, exclude I , O and U
- (b) Revision Code: cover all the change
- (c) Serial No.: Manufacturing sequence of product

11. PRECAUTIONS**11.1 ASSEMBLY AND HANDLING PRECAUTIONS**

- (1) The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2) While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3) Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5) If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6) Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9) Do not disassemble the module.
- (10) Do not pull or fold the lamp wire.
- (11) Pins of I/F connector should not be touched directly with bare hands.
- (12) Do not re-attach protective film onto the polarizer because of risk of bubble Mura and dust

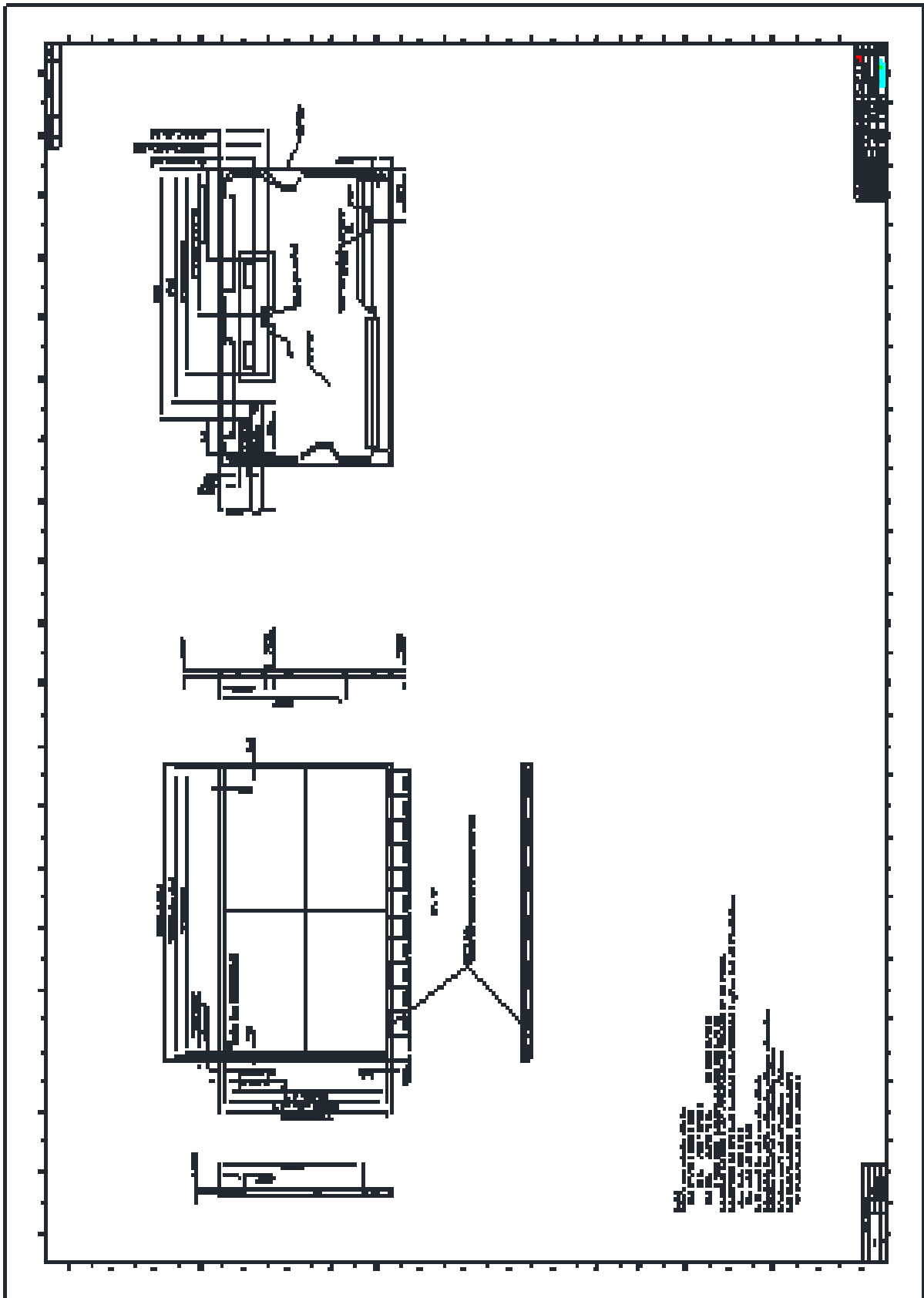
11.2 STORAGE PRECAUTIONS

- (1) When storing for a long time, the following precautions are necessary.
 - (a) Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 30°C at humidity 50+-10%RH.
 - (b) The polarizer surface should not come in contact with any other object.
 - (c) It is recommended that they be stored in the container in which they were shipped.
 - (d) Storage condition is guaranteed under packing conditions.
 - (e) The phase transition of Liquid Crystal in the condition of the low or high storage temperature will be recovered when the LCD module returns to the normal condition
- (2) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (3) It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (4) It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of lamp will be higher than the room temperature.




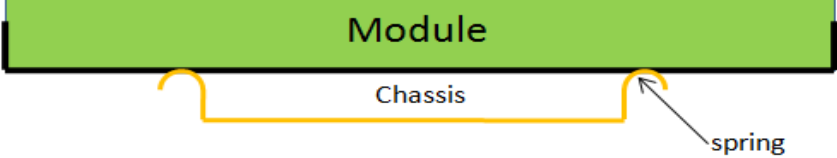
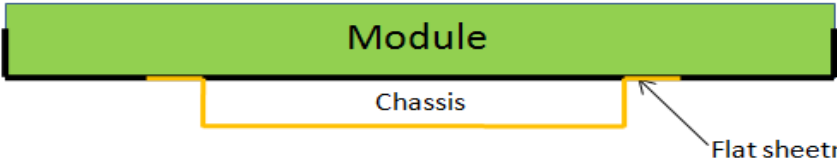
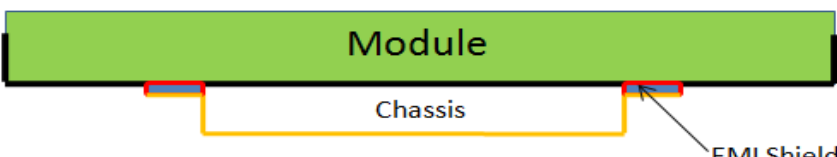
11.3 OTHER PRECAUTIONS

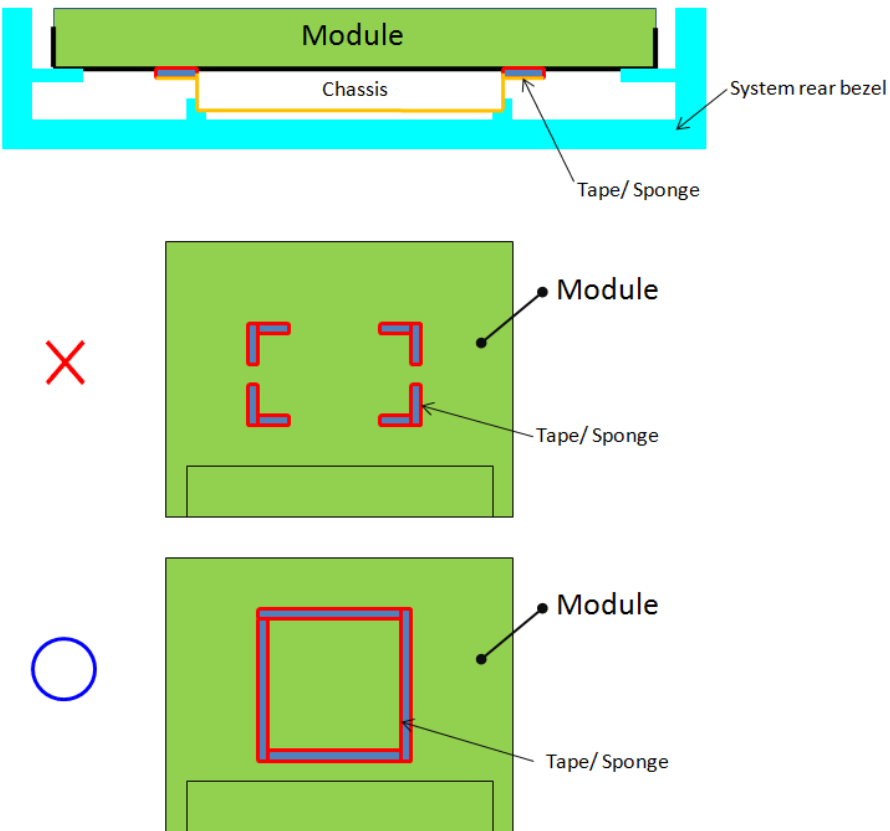
- (1) Normal operating condition
 - (a) Display pattern: dynamic pattern (Real display)
 - (Note) Long-term static display can cause image sticking.
- (2) Operating usages to protect against image sticking due to long-term static display
 - (a) Static information display recommended to use with moving image.
- (3) Abnormal condition just means conditions except normal condition.

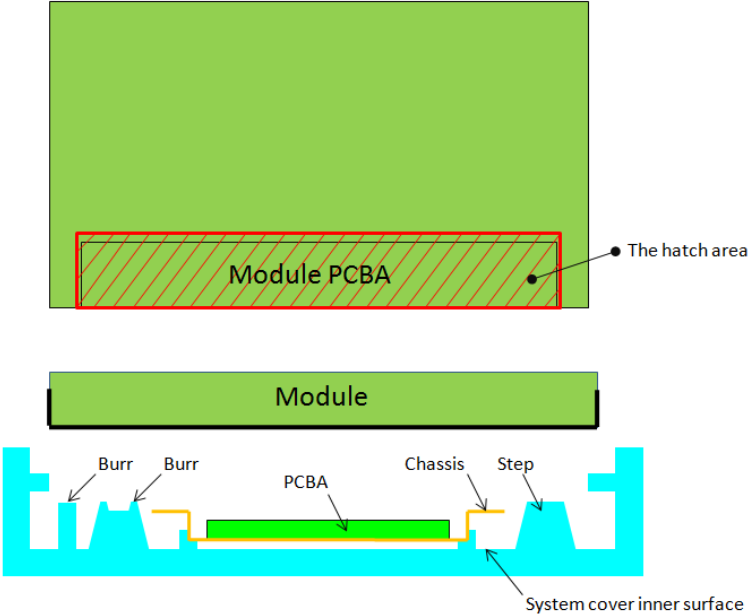
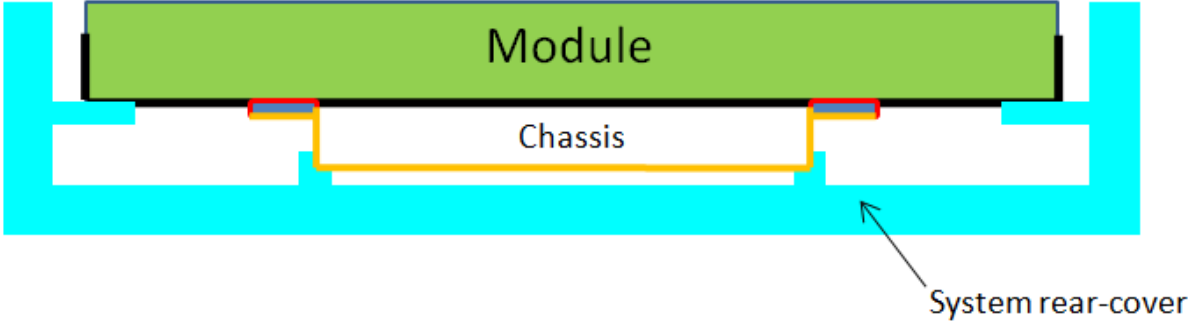
12. MECHANICAL CHARACTERISTICS

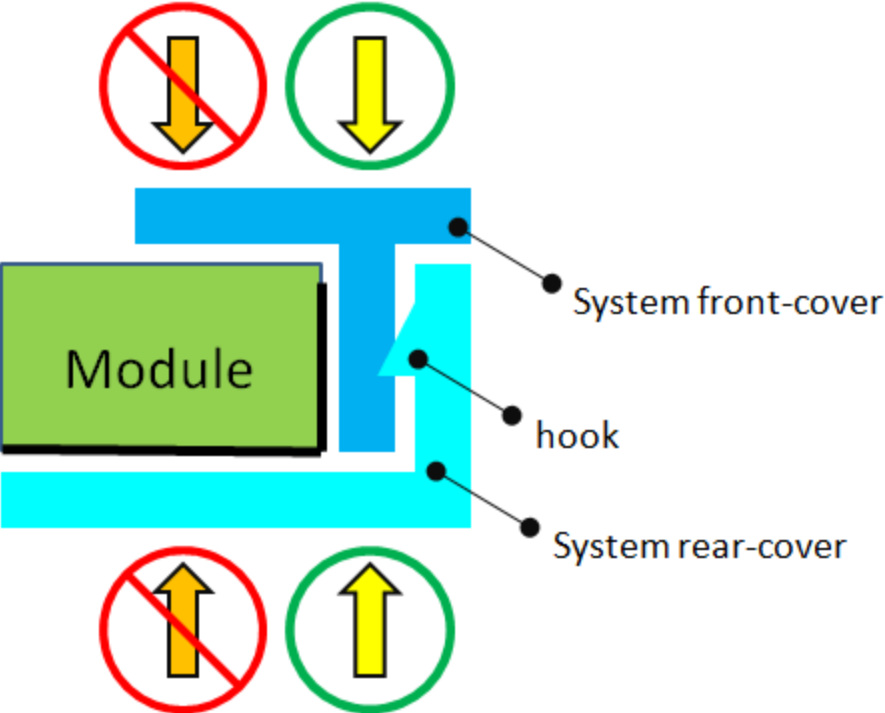


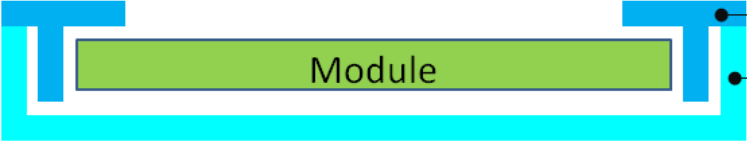
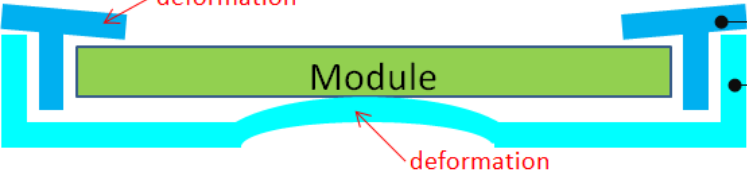
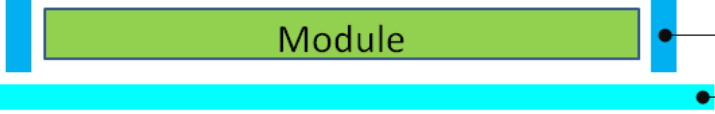
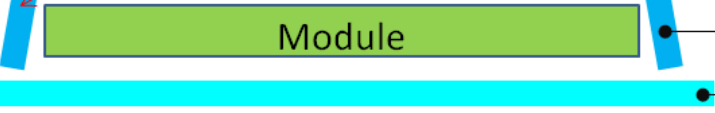
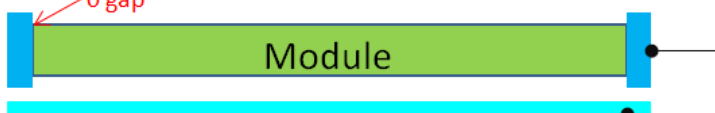
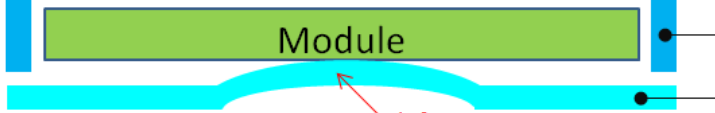
Appendix. SYSTEM COVER DESIGN NOTICE

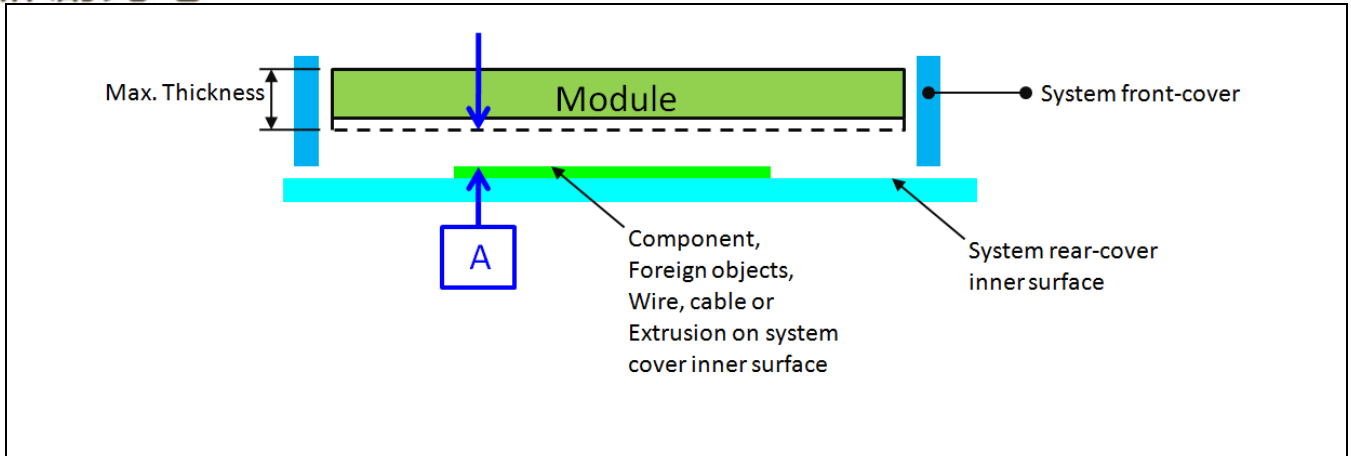
1	Set Chassis and IAVM Module touching Mode
  	  
Definition	<p>a. To prevent from abnormal display & white spot after mechanical test, it is not recommended to use spring type chassis.</p> <p>b. We suggest the contact mode between Chassis and Module rear cover is Tape/Sponge, second is Flat sheet metal type chassis.</p>

2	Tape/Sponge design on system inner surface
 <p>The diagrams illustrate the correct and incorrect placement of Tape/Sponge. The top diagram shows a cross-section where the Tape/Sponge is placed between the Module and the Chassis, with the System rear bezel on the right. The middle diagram shows a top view of the Module with Tape/Sponge pieces placed in separate locations, marked with a red 'X' to indicate it is incorrect. The bottom diagram shows a top view of the Module with Tape/Sponge forming a continuous frame around the Module, marked with a blue circle to indicate it is the correct design.</p>	
Definition	<p>a. To prevent from abnormal display & white spot after mechanical test, we suggest using Tape/Sponge as medium between chassis and Module rear cover could reduce the occurrence of white spot.</p> <p>b. When using the Tape/Sponge, we suggest it be lay over between set chassis and Module rear cover. It is not recommended to add Tape/Sponge in separate location. Since each Tape/Sponge may act as pressure concentration location.</p>

3	System inner surface examination
	
Definition	<p>a. The hatch area on Module PCBA should keep at least 1mm gap(X,Y,Z direction) to any structure with system cover inner surface.</p> <p>b. Burr, Step, PCB protrusion may cause stress concentration. White spot may occur during reliability test.</p>
4	Material used for system rear-cover
	
Definition	<p>System rear-cover material with high rigidity is needed to resist deformation during scuffing test, hinge test, pogo test or backpack test. Abnormal display, white spot, pooling issue may occur if low rigidity material is used. Pooling issue may occur because screw's boss position for module's bracket are deformed open-close test.</p> <p>Solid structure design of system rear-cover may also influence the rigidity of system rear-cover. The deformation of system rear-cover should not caused interference.</p>

5	Assembly SOP examination for system front-cover with hook structure
	
Definition	To prevent panel crack during system front-cover assembly process with hook structure, it is not recommended to press panel or any location that relate directly to the panel.
6	Permanent deformation of system cover after reliability test

<p>○</p>	 <p>● System front-cover ● System rear-cover</p>
<p>×</p>	 <p>● System front-cover ● System rear-cover</p>
<p>○</p>	 <p>● System front-cover ● System rear-cover</p>
<p>×</p>	 <p>● System front-cover ● System rear-cover</p>
<p>×</p>	 <p>● System front-cover ● System rear-cover</p>
<p>×</p>	 <p>● System front-cover ● System rear-cover</p>
<p>Definition</p>	<p>System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell crack.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>
<p>7</p>	<p>Design gap A between panel & any components on system rear-cover</p>

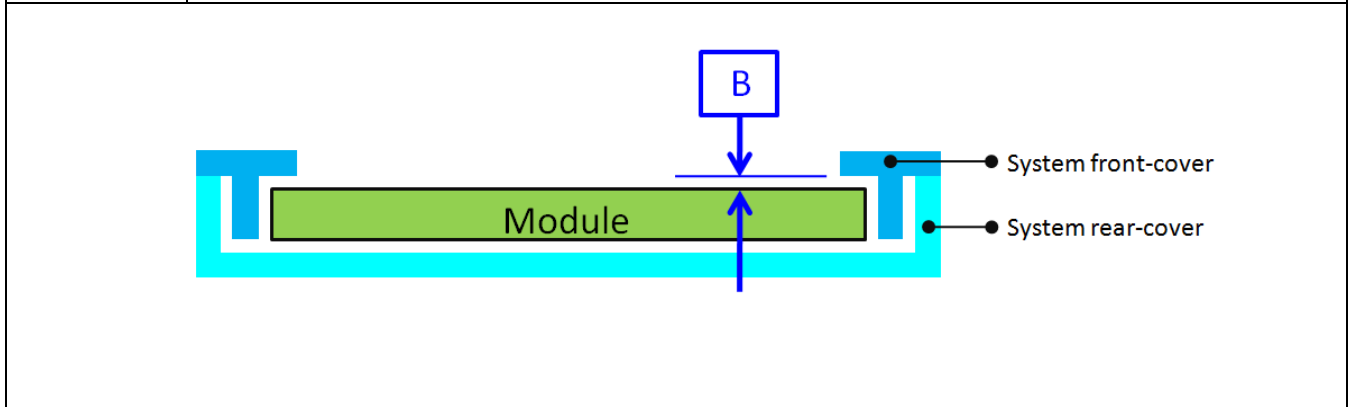


Definition

System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell creak.

Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.

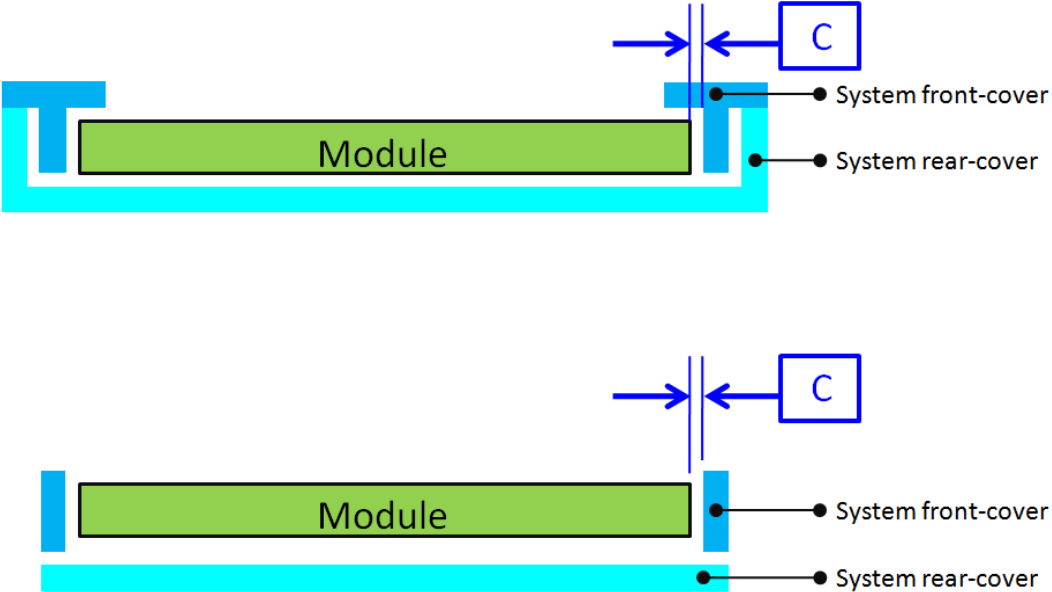
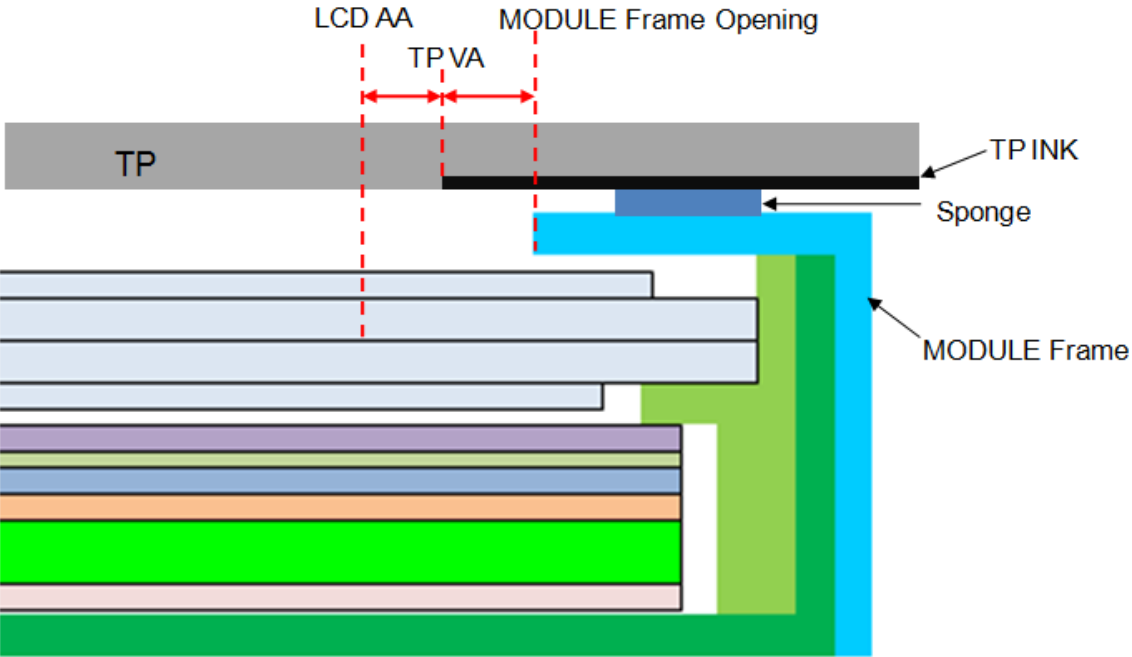
8 Design gap B between system front-cover & panel surface



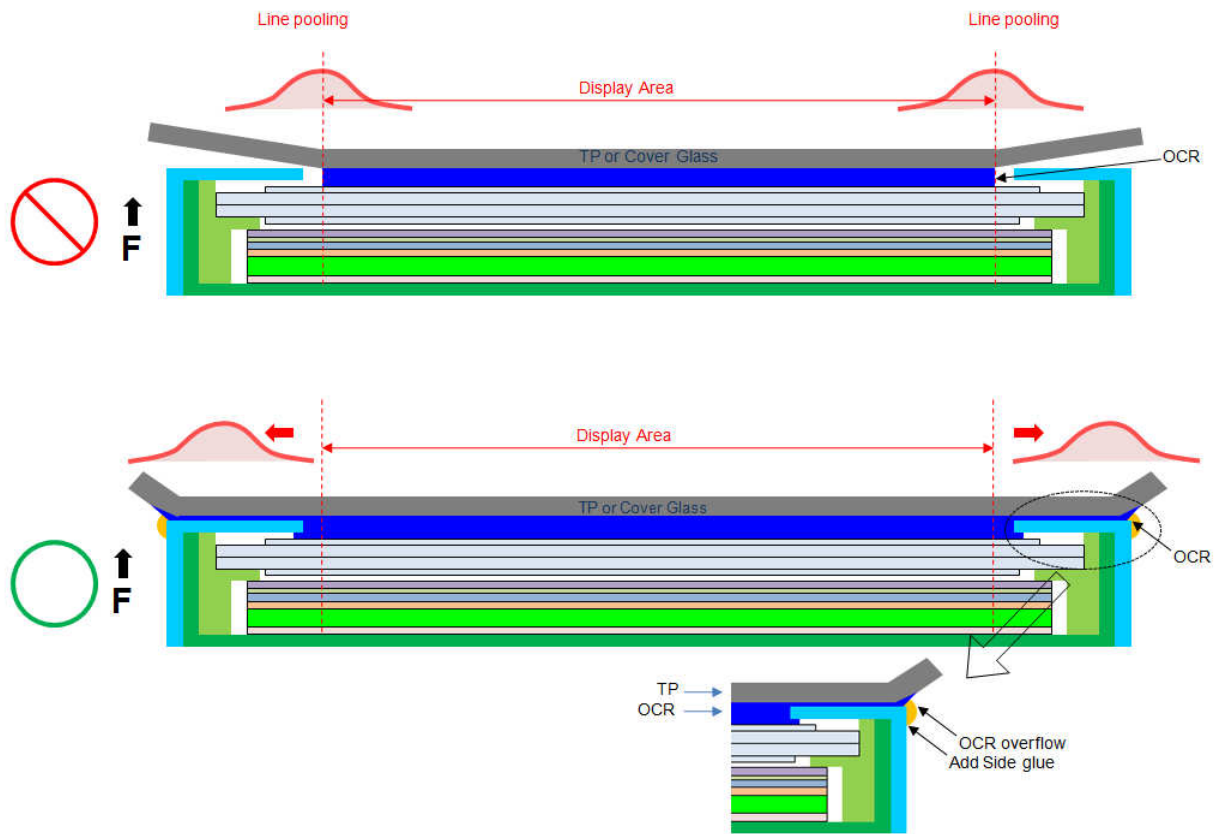
Definition

Gap between system front-cover & panel surface is needed to prevent pooling or glass broken. Zero gap or interference such as burr and warpage from mold frame may cause pooling issue near system front-cover opening edge. This phenomenon is obvious during swing test, hinge test, knock test or during pooling inspection procedure. To remain sufficient gap, design with system rib higher than maximum panel thickness is recommended.

Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.

9	Design gap C between panel & system front-cover or protrusions
	 <p>The top diagram shows a green 'Module' positioned between a cyan 'System front-cover' and a cyan 'System rear-cover'. A blue double-headed arrow labeled 'C' indicates the gap between the module and the front cover. The bottom diagram shows the green 'Module' between a cyan 'System front-cover' and a cyan 'System rear-cover' protrusion. A blue double-headed arrow labeled 'C' indicates the gap between the module and the front cover.</p>
Definition	<p>Gap between panel & system front-cover or protrusions is needed to prevent shock test failure. Because system front-cover or protrusions with small gap may hit panel during the test. Issue such as cell crack, abnormal display may occur. The gap should be large enough to absorb the maximum displacement during the test. Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>
10	Design distance between TP AA to LCD AA
	 <p>The diagram shows a cross-section of the display assembly. From top to bottom, the layers are: TP (Touch Panel), TP VA (TP with VA), TP INK (TP with ink), Sponge, and MODULE Frame. Below the sponge is the LCD AA (Active Area) and the MODULE Frame Opening. A red double-headed arrow indicates the distance between the TP VA and the LCD AA. Labels include: LCD AA, MODULE Frame Opening, TP VA, TP, TP INK, Sponge, and MODULE Frame.</p>

Definition	TP VA should avoid TP ink area covering LCD AA or causing the module frame to be exposed.
11	Use OCR Lamination



Definition	1.OCR glue as possible beyond module, in order to avoid Line Pooling 2.Add side glue to avoid Line Pooling
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